#### September 2006 Advance Information



#### AS7C1029

#### 5V 256K X 4 CMOS SRAM (Center power and ground)

#### **Features**

- Industrial (-40° to 85°C) temperature.
- Organization: 262,144 x 4 bits
- High speed
- 12 ns address access time
- 6 ns output enable access time
- Low power consumption via chip deselect
- Easy memory expansion with  $\overline{CE}$ ,  $\overline{OE}$  inputs
- Center power and ground
- TTL/LVTTL-compatible, three-state I/O

- JEDEC-standard package
- 32-pin, 400 mil SOJ
- ESD protection  $\geq 2000$  volts

#### **Pin arrangement**

#### Logic block diagram



## 32-pin SOJ (400 mil)

NC		1		32		A17
A0		2 3		31		A16
A1		3		30		A15
A2		4		29		A14
A3		5	စ္မ	28		A13
CE		6	8	27		OE
I/O0		7	ž	26		I/O3
V <sub>CC</sub>		8	Ω.	25		GND
GND		9	S7C1029	24		V <sub>CC</sub>
I/O1		10	Ä	23		I/02
WE		11		22		A12
A4		12		21		A11
A5	_	13		20		A10
A6	_	14		19		A9
A7	_	15		18		A8
NC		16		17	E	NC
				17		NC

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#### **Functional description**

The AS7C1029 is a 5V high-performance CMOS 1,048,576-bit Static Random Access Memory (SRAM) devices organized as 262,144 x 4 bits. They are designed for memory applications where fast data access, low power, and simple interfacing are desired.

Equal address access and cycle times ( $t_{AA}$ ,  $t_{RC}$ ,  $t_{WC}$ ) of 12 ns with output enable access times ( $t_{OE}$ ) of 6 ns are ideal for highperformance applications. The chip enable input  $\overline{CE}$  permits easy memory and expansion with multiple-bank memory systems.

When  $\overline{CE}$  is high, the device enters standby mode. If inputs are still toggling, the device will consume I<sub>SB</sub> power. If the bus is static, then full standby power is reached (I<sub>SB1</sub>).

A write cycle is accomplished by asserting write enable ( $\overline{WE}$ ) and chip enable ( $\overline{CE}$ ). Data on the input pins I/O0 through I/O7 is written on the rising edge of  $\overline{WE}$  (write cycle 1) or  $\overline{CE}$  (write cycle 2). To avoid bus contention, external devices should drive I/O pins only after outputs have been disabled with output enable ( $\overline{OE}$ ) or write enable ( $\overline{WE}$ ).

A read cycle is accomplished by asserting output enable ( $\overline{OE}$ ) and chip enable ( $\overline{CE}$ ), with write enable ( $\overline{WE}$ ) high. The chips drive I/O pins with the data word referenced by the input address. When either chip enable or output enable is inactive or write enable is active, output drivers stay in high-impedance mode.

All chip inputs and outputs are TTL-compatible, and operation is from a single 5 V supply. The AS7C1029 is packaged in common industry standard packages.

Parameter	Symbol	Min	Max	Unit
Voltage on V <sub>CC</sub> relative to GND	V <sub>t1</sub>	-0.50	+7.0	V
Voltage on any pin relative to GND	V <sub>t2</sub>	-0.50	V <sub>CC</sub> + 0.5	V
Power dissipation	P <sub>D</sub>	_	1.25	W
Storage temperature (plastic)	T <sub>stg</sub>	-55	+125	° C
Ambient temperature with V <sub>CC</sub> applied	T <sub>bias</sub>	-55	+125	° C
DC current into outputs (low)	I <sub>OUT</sub>	_	50	mA

#### Absolute maximum ratings

Notes:

Stresses greater than those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions outside those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

#### **Truth table**

CE	WE	OE	Data	Mode
Н	Х	Х	High Z	Standby (I <sub>SB</sub> , I <sub>SB1</sub> )
L	Н	Н	High Z	Output disable (I <sub>CC</sub> )
L	Н	L	D <sub>OUT</sub>	Read (I <sub>CC</sub> )
L	L	Х	D <sub>IN</sub>	Write (I <sub>CC</sub> )

Key: X = don't care, L = low, H = high.

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#### **Recommended operating conditions**

Parameter	Symbol	Min	Nominal	Max	Unit
Supply voltage	V <sub>CC</sub>	4.5	5.0	5.5	V
Input voltage	V <sub>IH</sub>	2.2	-	$V_{CC} + 0.5$	V
input voluge	V <sub>IL</sub>	-0.5	-	0.8	V
Ambient operating temperature (Industrial)	T <sub>A</sub>	-40	_	85	° C

Notes:

 $V_{IL}$  min = -1.5V for pulse width less than 5ns, once per cycle.

 $V_{IH}\,max = V_{CC}\!\!+\!\!2.0V$  for pulse width less than 5ns, once per cycle.

#### DC operating characteristics (over the operating range) $^{I}$

			AS7C1	029-12	
Parameter	Symbol	Test conditions	Min	Max	Unit
Input leakage current	I <sub>LI</sub>	$V_{CC} = Max$ , $V_{IN} = GND$ to $V_{CC}$	-	5	μΑ
Output leakage current	I <sub>LO</sub>	$V_{CC} = Max, \overline{CE} = V_{IH},$ $V_{out} = GND \text{ to } V_{CC}$	-	5	μΑ
Operating power supply current	I <sub>CC</sub>	$\label{eq:VCC} \begin{split} & V_{CC} = Max \\ & \overline{CE} \leq V_{IL},  f = f_{Max}, I_{OUT} = 0 \; mA \end{split}$	_	160	mA
Standby power supply current <sup>1</sup>	I <sub>SB</sub>	$\label{eq:CC} \begin{split} & V_{CC} = Max \\ & \overline{CE} \geq V_{IH},  f = f_{Max} \end{split}$	-	40	mA
	I <sub>SB1</sub>	$\begin{split} & \frac{V_{CC} = Max}{CE} \geq V_{CC} - 0.2 \text{ V}, \\ & V_{IN} \leq 0.2 \text{ V or } V_{IN} \geq V_{CC} - 0.2 \text{ V}, \\ & f = 0 \end{split}$		10	mA
Output voltage	V <sub>OL</sub>	$I_{OL} = 8 \text{ mA}, V_{CC} = Min$	-	0.4	V
ouput voluge	V <sub>OH</sub>	$I_{OH} = -4 \text{ mA}, V_{CC} = Min$	2.4	-	V

### **Capacitance** $(f = 1 \text{ MHz}, T_a = 25^{\circ} \text{ C}, V_{CC} = \text{NOMINAL})^2$

Parameter	Symbol	Signals	Test conditions	Max	Unit
Input capacitance	C <sub>IN</sub>	A, $\overline{CE}$ , $\overline{WE}$ , $\overline{OE}$	$V_{IN} = 3dV$	8	pF
I/O capacitance	C <sub>I/O</sub>	I/O	$V_{IN} = V_{OUT} = 3dV$	8	pF

Note:

This parameter is guaranteed by device characterization, but is not production tested.

## **Read cycle (over the operating range)**<sup>3,9</sup>

		AS7C1029-12			
Parameter	Symbol	Min	Max	Unit	Notes
Read cycle time	t <sub>RC</sub>	12	—	ns	
Address access time	t <sub>AA</sub>	-	12	ns	3
Chip enable $(\overline{CE})$ access time	t <sub>ACE</sub>	-	12	ns	3
Output enable $(\overline{OE})$ access time	t <sub>OE</sub>	-	6	ns	
Output hold from address change	t <sub>OH</sub>	4	-	ns	5
$\overline{\text{CE}}$ low to output in low Z	t <sub>CLZ</sub>	3	-	ns	4, 5
CE low to output in high Z	t <sub>CHZ</sub>	0	6	ns	4, 5
OE low to output in low Z	t <sub>OLZ</sub>	0	_	ns	4, 5
OE high to output in high Z	t <sub>OHZ</sub>	0	5	ns	4, 5
Power up time	t <sub>PU</sub>	0	-	ns	4, 5
Power down time	t <sub>PD</sub>	-	12	ns	4, 5

#### Key to switching waveforms



Undefined/don't care

#### Read waveform 1 (address controlled)<sup>3,6,7,9</sup>



#### Read waveform 2 (CE and OE controlled)<sup>3,6,8,9</sup>



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#### Write cycle (over the operating range)<sup>11</sup>

		AS7C1029-12			
Parameter	Symbol	Min	Max	Unit	Notes
Write cycle time	t <sub>WC</sub>	12	—	ns	
Chip enable $(\overline{CE})$ to write end	t <sub>CW</sub>	10	-	ns	
Address setup to write end	t <sub>AW</sub>	10	-	ns	
Address setup time	t <sub>AS</sub>	0	-	ns	
Write pulse width	t <sub>WP</sub>	10	-	ns	
Write recovery time	t <sub>WR</sub>	0	-	ns	
Address hold from end of write	t <sub>AH</sub>	0	-	ns	
Data valid to write end	t <sub>DW</sub>	7	_	ns	
Data hold time	t <sub>DH</sub>	0	-	ns	4, 5
Write enable to output in high Z	t <sub>WZ</sub>	0	5	ns	4, 5
Output active from write end	t <sub>OW</sub>	3	_	ns	4, 5

### Write waveform 1 (WE controlled)<sup>10,11</sup>



#### Write waveform 2 (CE controlled)<sup>10,11</sup>



### AC test conditions

- Output load: see Figure B.
- Input pulse level: GND to 3.0 V. See Figure A.
- Input rise and fall times: 3 ns. See Figure A.
- Input and output timing reference levels: 1.5 V.



#### Notes:

- 1 During  $V_{CC}$  power-up, a pull-up resistor to  $V_{CC}$  on  $\overline{CE}$  is required to meet  $I_{SB}$  specification.
- 2 This parameter is sampled, but not 100% tested.
- 3 For test conditions, see *AC Test Conditions*, Figures A and B.
- 4  $t_{CLZ}$  and  $t_{CHZ}$  are specified with CL = 5 pF, as in Figure B. Transition is measured ±200 mV from steady-state voltage.
- 5 This parameter is guaranteed, but not 100% tested.
- $\overline{\text{WE}}$  is high for read cycle.
- 7  $\overline{\text{CE}}$  and  $\overline{\text{OE}}$  are low for read cycle.
- 8 Address is valid prior to or coincident with  $\overline{\text{CE}}$  transition low.
- 9 All read cycle timings are referenced from the last valid address to the first transitioning address.
- 10 N/A
- 11 All write cycle timings are referenced from the last valid address to the first transitioning address.
- 12 N/A.
- 13 C = 30 pF, except all high Z and low Z parameters where C = 5 pF.

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#### Package dimensions



	32-pin SOJ 400 mil			
Symbol	Min	Max		
A	0.132	0.146		
A1	0.025	-		
A2	0.105	0.115		
B	0.026	0.032		
b	0.015	0.020		
с	0.007	0.013		
D	0.820	0.830		
E	0.354	0.378		
<b>E1</b>	0.395	0.405		
<b>E2</b>	0.435	0.445		
e	0.050	BSC		

Note: This part is compatible with both pin numbering conventions used by various manufacturers.

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### **Ordering Codes**

Package	Volt/Temp	12 ns
Plastic SOJ, 400 mil	5V industrial	AS7C1029-12JIN

#### Part numbering system

Γ	AS7C	<b>1029C</b>	-XX	X	X	X
	SRAM prefix	Device number	Access time		Temperature range I = industrial, $-40^{\circ}$ C to $85^{\circ}$ C	N = LEAD FREE PART



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